WHAT IS CLAIMED IS:

- 1. A process for treating a substrate with plasma comprising: generating said plasma in the form of plane in a chamber.
- 2. The process of claim 1 further comprising moving said substrate through said plasma in a direction perpendicular to said plane of said plasma to treat said substrate with said plasma.
 - 3. The process of claim 2 wherein pressure in said chamber is in the range of from 0.1 to 800 Torr.
- 4. The process of claim 2 wherein a starting material gas is flown into said plasma in a direction parallel to said plane of said plasma from at least one gas supply slit provided in a ground electrode provided in said chamber.
 - 5. The process of claim 2 wherein said plasma has a cross section in parallel to said substrate at a ratio (length thereof)/(width thereof) of 10 or more.
- 6. The process of claim 4 wherein said gas supply slit has a ratio (length thereof)/(width thereof) of 5 or more.
 - 7. The process of claim 2 wherein a starting material gas is flown into said plasma in a direction parallel to said plane of said plasma from a plurality of gas supply ports arranged on a line and provided in a ground electrode provided in said chamber.
- 8. A process for depositing a diamond-like carbon film comprising:
 generating a plasma in the form of plane in a chamber for depositing
 said diamond-like carbon film; and moving a substrate through said plasma in a

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direction perpendicular to said plane of said plasma to deposit said diamond-like carbon film an said substrate.

- 9. The process of claim 8 wherein pressure in said chamber is in the range of from 0.1 to 800 Torr.
- 10. The process of claim 8 wherein a starting material gas is flown into said plasma in a direction parallel to said plane of said plasma from at least one gas supply slit provided in a ground electrode provided in said chamber.
- 11. The process of claim 8 wherein a starting material gas is flown into said plasma in a direction parallel to said plane of said plasma from a plurality of gas supply ports arranged on a line and provided in a ground electrode provided in said chamber.
- 12. The process of claim 10 wherein said starting material gas comprises $Si(C_xH_{2x+1})_{4-y}H_y$ where x is an integer of 1-or more, and y is an integer from 0 to 3.
 - 13. The process of claim & wherein said plasma contains a methyl group.
- 14. A method for forming a djamond-like carbon film by a roll-to-roll apparatus comprising:
 - a feeding roll for feeding an organic resin film therefrom;
 - a winding roll -for winding said organic resin film therearound; and at least one chamber for forming said diamond-like carbon film, said
- 20 method comprising:
 - revolving said winding roll to wind said organic resin film therearound so that said organic resin film is passed through said at least one chamber; and

forming said diamond-like carbon film in said at least one chamber by a plasma generated in the form of plane in said at least one chamber during said revolving step.

- 15. The method of claim 14 wherein said organic resin film has a magnetic layer provided thereon, and said diamond -like carbon film is formed on said magnetic layer.
- 16. An apparatus for fabricating a magnetic recording medium by sequentially and continuously forming a magnetic layer and a diamond-like carbon film on a polymer substrate material, said apparatus comprising:

a first vacuum vessel for forming the magnetic layer of the magnetic recording medium; and

a second vacuum vessel/for forming the diamond-like carbon film, wherein the pressure difference between the operation pressures for the first vessel and the second vessel is set in the range of from 10⁻² to 10⁻⁵ Torr.

17. The apparatus of claim 16 further comprising a third vacuum vessel for performing plasma activation treatment between the first vessel and the second vacuum vessel.

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